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November 2013

FDP039N08B

N-Channel PowerTrench[®] MOSFET 80 V, 171 A, 3.9 m Ω

Features

- $R_{DS(on)}$ = 3.16 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 100 A
- Low FOM R_{DS(on)} * Q_G
- Low Reverse-Recovery Charge, Q_{rr} = 87.9 nC
- · Soft Reverse-Recovery Body Diode
- Enables High Efficiency in Synchronous Rectification
- · Fast Switching Speed
- · 100% UIL Tested
- · RoHS Compliant

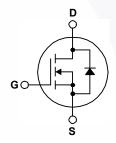
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor Drives and Uninterruptible Power Supplies





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDP039N08B_F102	Unit
V _{DSS}	Drain to Source Voltage		80	V
V _{GSS}	Gate to Source Voltage		±20	V
		- Continuous (T _C = 25°C, Silicon Limited)	171*	
I _D	Drain Current	- Continuous (T _C = 100°C, Silicon Limited)	121*	Α
		- Continuous (T _C = 25°C, Package Limited)	120	
I _{DM}	Drain Current	- Pulsed (Note 1)	684	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		547	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns
D	Dower Dissipation	(T _C = 25°C)	214	W
P_{D}	Power Dissipation	- Derate Above 25°C	1.43	W/°C
T _J , T _{STG}	Operating and Storage Tempera	-55 to +175	οС	
TL	Maximum Lead Temperature for	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		

^{*} Package limitation current is 120A.

Thermal Characteristics

Symbol	Parameter FDP039N08B_F		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. 62.5		*0/00

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDP039N08B_F102	FDP039N08B	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}$	80	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	0.089	-	V/°C
	Zero Gate Voltage Drain Current	V _{DS} = 64 V, V _{GS} = 0 V	-	-	1	^
DSS	Zero Gate Voltage Drain Current	$V_{DS} = 64 \text{ V}, T_{C} = 150^{\circ}\text{C}$	-	-	500	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 100 A	-	3.16	3.9	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 100 A	-	180	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 40 V V 0 V	-	7105	9450	pF
C _{oss}	Output Capacitance	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	1110	1475	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 WH 12	- \	30	-	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 40 V, V _{GS} = 0 V	-	1656	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	102	133	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 40 \text{ V}, I_{D} = 100 \text{ A},$		39.9	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10 V	-	22	-	nC
V _{plateau}	Gate Plateau Volatge	(Note 4)	-	5.6	-	V
Q _{sync}	Total Gate Charge Sync.	V _{DS} = 0 V, I _D = 50 A	-	87.4	-	nC
Q _{oss}	Output Charge	V _{DS} = 40 V, V _{GS} = 0 V	-	99.2	-	nC

Switching Characteristics

•						
t _{d(on)}	Turn-On Delay Time		-/	36	82	ns
t _r	Turn-On Rise Time	V _{DD} = 40 V, I _D = 100 A,	-	49	108	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω	/ -	71	152	ns
t _f	Turn-Off Fall Time	(Note 4)	-	29	68	ns
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	2.2	-	Ω

Drain-Source Diode Characteristics

Is	Maximum Continuous Drain to Source Diode Forward Current			-	171*	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		1	-	684	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 100 A	1	-	1.3	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, V_{DD} = 40 \text{ V}, I_{SD} = 100 \text{ A},$	-	70.1	//-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	87.9	-	nC

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 3 mH, I_{AS} = 19.1 A, starting T_J = 25°C.
- 3. I_{SD} \leq 100 A, di/dt \leq 200 A/ μ s, V_{DD} \leq BV_DSS, starting T_J = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

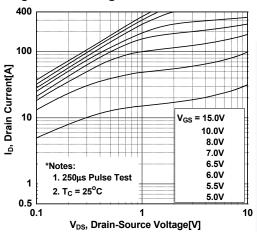


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

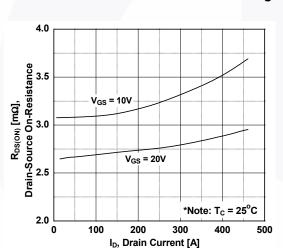


Figure 5. Capacitance Characteristics

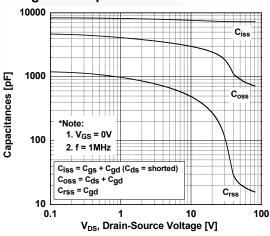


Figure 2. Transfer Characteristics

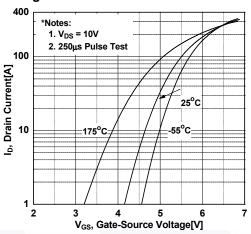


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

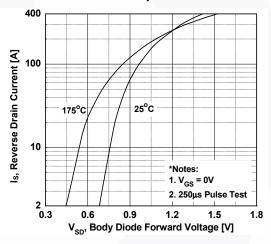
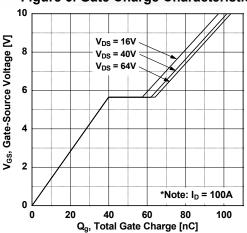


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

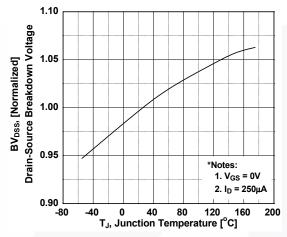


Figure 9. Maximum Safe Operating Area

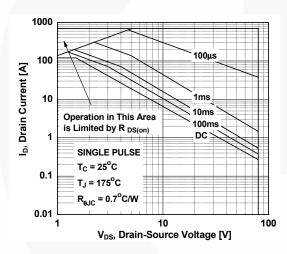


Figure 11. Eoss vs. Drain to Source Voltage

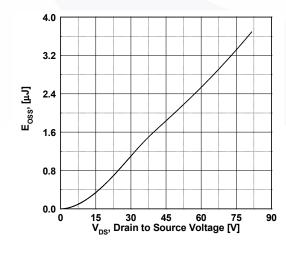


Figure 8. On-Resistance Variation vs. Temperature

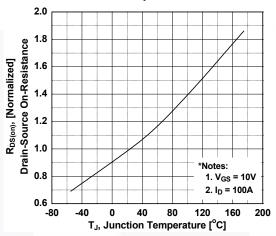


Figure 10. Maximum Drain Current vs. Case Temperature

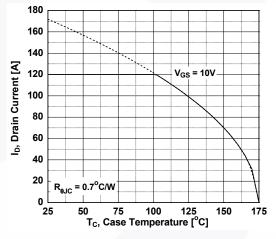
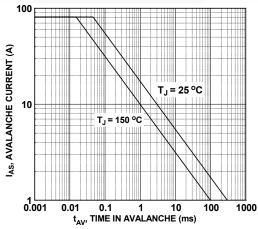
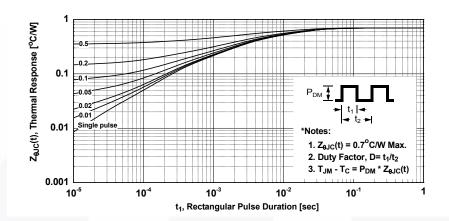


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve



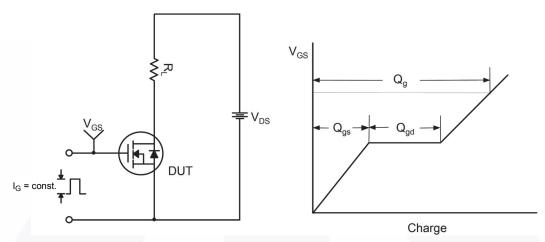


Figure 14. Gate Charge Test Circuit & Waveform

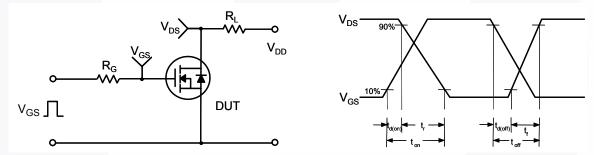


Figure 15. Resistive Switching Test Circuit & Waveforms

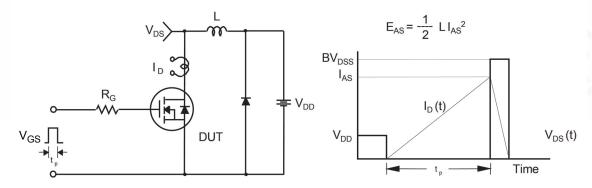


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

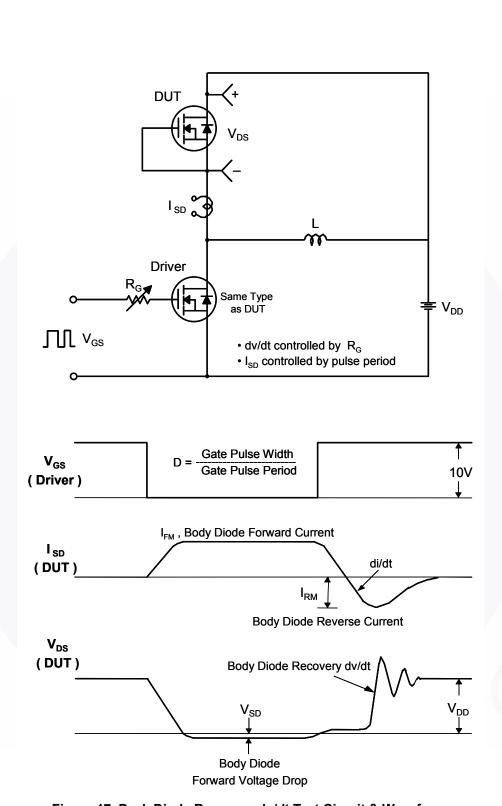


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

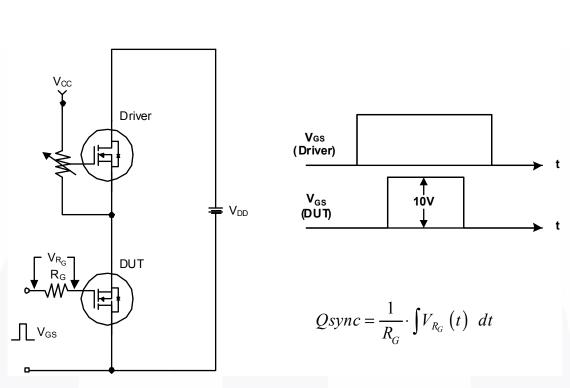


Figure 18. Total Gate Charge Qsync. Test Circuit & Waveforms

Mechanical Dimensions

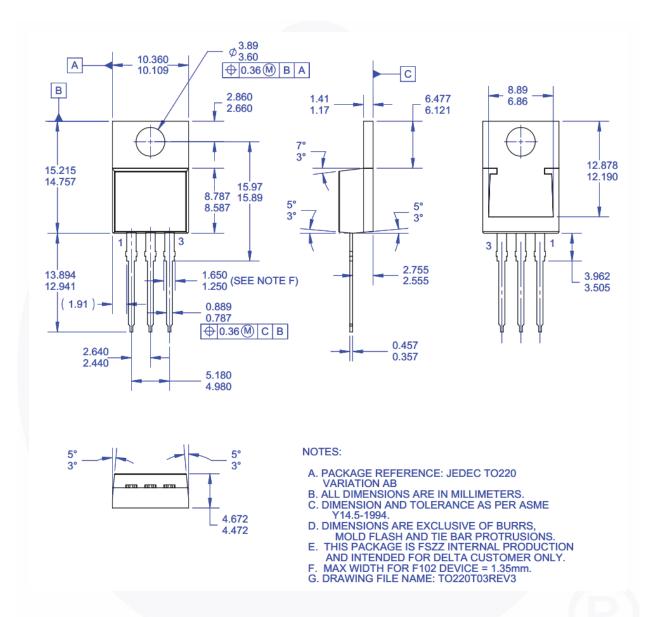


Figure 19. TO-220, Molded, 3-Lead, Jedec Variation AB (Delta)

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